TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (π-MOSIV)

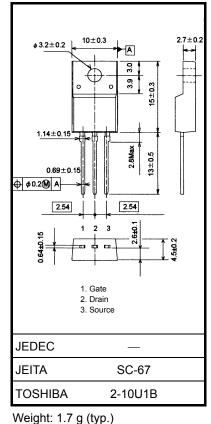
2SK3799

Switching Regulator Applications

- Low drain-source ON resistance $: RDS (ON) = 1.0 \Omega (typ.)$
- High forward transfer admittance $|Y_{fs}| = 6.0 \text{ S (typ.)}$
- Low leakage current $: I_{DSS} = 100 \,\mu \text{ A} (\text{max}) (V_{DS} = 720 \text{ V})$
- Enhancement model $: V_{th} = 2.0 \text{ to } 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ID} = 1 \text{ mA})$

Characteristic Symbol Rating Unit Drain-source voltage VDSS 900 V V Drain-gate voltage (R_{GS} = 20 kΩ) 900 VDGR V Gate-source voltage V_{GSS} ±30 DC (Note 1) 8 А I_D Drain current Pulse (Note 1) 24 А I_{DP} Drain power dissipation P_D 50 w Single pulse avalanche energy 1080 mJ EAS (Note 2) Avalanche current 8 IAR Α Repetitive avalanche energy (Note 3) EAR 5 mJ °C Channel temperature 150 T_{ch} Storage temperature range -55~150 °C T_{stg}

Absolute Maximum Ratings (Ta = 25°C)



Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Thermal Characteristics

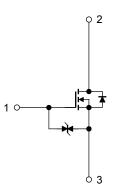
Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch−c)}	2.5	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	62.5	°C / W

Note 1: Ensure that the channel temperature does not exceed 150°C during use of the device.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 30.9 mH, R_G = 25 Ω , I_{AR} = 8 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature.

This transistor is an electrostatic-sensitive device. Handle with care.



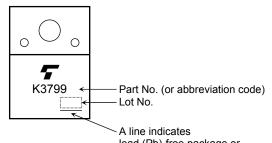
Electrical Characteristics (Ta = 25°C)

Chara	cteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	irrent	I _{GSS}	V_{GS} = ±30 V, V_{DS} = 0 V	_	_	±10	μA
Drain-source bre	eakdown voltage	V _(BR) GSS	I_{G} = ±10 µA, V_{GS} = 0 V	±30	_	_	V
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	100	μA
Drain-source bre	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	450	_		V
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source ON	V resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 4 A	—	1.0	1.3	Ω
Forward transfer	r admittance	Y _{fs}	V _{DS} = 15 V, I _D = 4 A	3.5	6.0		S
Input capacitance	e	C _{iss}		—	2200		
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	—	45		pF
Output capacitance		C _{oss}		—	190		
Switching time	Rise time	tr	$V_{GS} = 4 A$ $V_{GS} = 4 A$ $V_{GS} = 4 A$ $V_{DD} \approx 400 V$	_	25	_	. ns
	Turn-on time	t _{on}		—	65		
	Fall time	t _f		_	20	_	
	Turn-off time	t _{off}	Duty ≤ 1%, t _w = 10 µs	_	120		
Total gate charge (Gate-source plus gate-drain)		Qg	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 8 A	_	60	_	
Gate-source charge		Q _{gs}		_	34	_	nC
Gate-drain ("miller") charge		Q _{gd}		_	26	—	

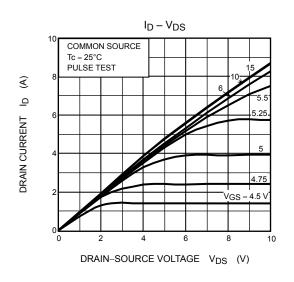
Source-Drain Ratings and Characteristics (Ta = 25°C)

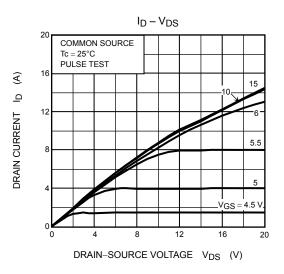
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	8	А
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	24	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 8 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 8 A, V _{GS} = 0 V		1700		ns
Reverse recovery charge	Qrr	dl _{DR} / dt = 100 A / μS	_	23	_	μC

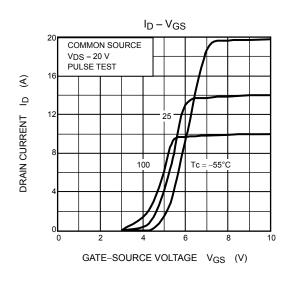
Marking

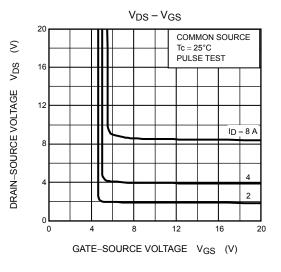


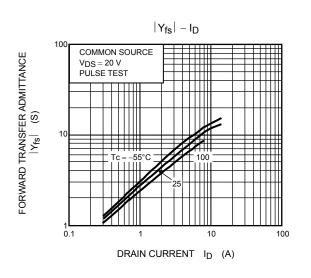
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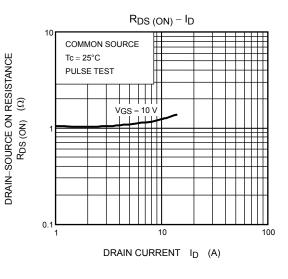




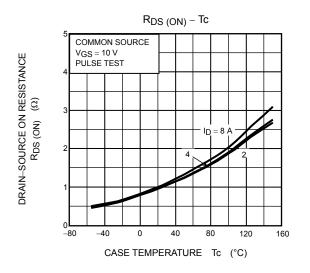


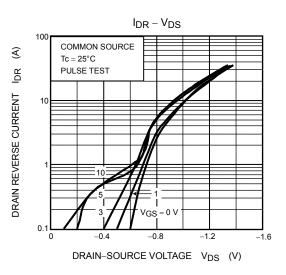


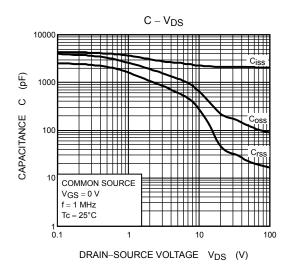


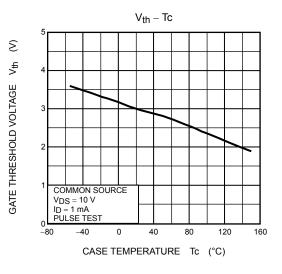


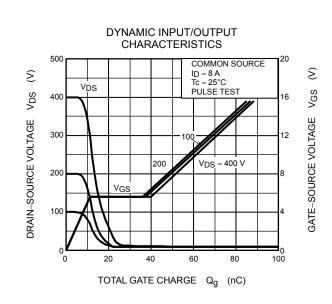
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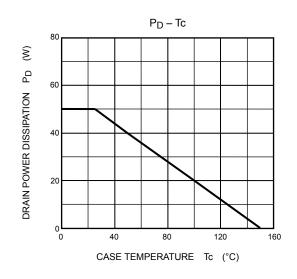


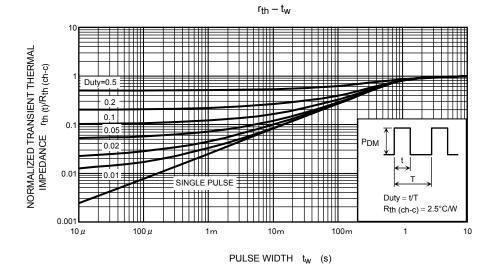








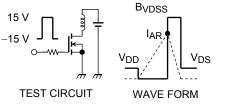




SAFE OPERATING AREA 100 ID max (PULSE) 00 ON € 1(DRAIN CURRENT ID DC OPERATION $Tc = 25^{\circ}C$ 0.1 SINGLE NONPETITIVE PULSE $Tc = 25^{\circ}C$ Curves must be derated linearly VDSS max with increase in temperature 0.01 10 100 1000 10000 1

DRAIN–SOURCE VOLTAGE V_{DS} (V)

 $E_{AS} - T_{ch}$ 2000 (ſш) 1600 AVALANCHE ENERGY EAS 1200 800 400 0 L 25 50 75 100 125 150 CHANNEL TEMPERATURE (INITIAL) T_{ch} (°C)



 $R_G = 25 \ \Omega$ V_{DD} = 90 V, L = 30.9 mH

 $E_{AS} = \frac{1}{2} \cdot L \cdot l^2 \cdot$ $\left(\frac{\mathsf{B}\mathsf{V}\mathsf{D}\mathsf{S}\mathsf{S}}{\mathsf{B}\mathsf{V}\mathsf{D}\mathsf{S}\mathsf{S}}-\mathsf{V}\mathsf{D}\mathsf{D}\right)$

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